

Customer No.: 31561
Application No.: 10/709,179
Docket No.: 10544-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

Claims 1-14 (canceled).

Claim 15 (original) A method of fabricating bumps on the backside of a chip, comprising the steps of:

providing a chip with an active surface having a plurality of bonding pads thereon and a backside;

forming at least a bump pad on the backside of the chip; and

attaching a bump to the bump pad.

Claim 16 (original) The method of claim 15, wherein the step of forming the bump pad on the backside of the chip further comprises:

forming a metallic layer on the backside of the chip; and

patterning the metallic layer to form the bump pad.

Claim 17 (original) The method of claim 15, wherein the step of forming the bump pad on the backside of the chip further comprises:

putting a mask on the backside of the chip, wherein the mask has at least an opening so that the backside of the chip is exposed;

forming a metallic layer over the mask and the exposed backside of the chip;

and

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removing the mask so that the remaining metallic layer on the backside of the chip becomes the bump pad.

Claim 18 (original) The method of claim 15, wherein before forming the bump pad on the backside of the chip, the method further comprises forming a protective film on the active surface of the chip.

Claim 19 (original) The method of claim 15, wherein the chip further comprises a passivation layer coated on the backside of the chip so that the passivation layer is removed before forming the bump pad on the backside of the chip.

Claim 20 (original) The method of claim 15, wherein during the step of attaching bumps to the bump pads, patterning and electroplating process, a printing process, a bump-bonding process by a wire-bonding machine or a ball-implanting process are

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